

Title (en)

METHOD OF SEALING OR WELDING TWO ELEMENTS TO ONE ANOTHER

Title (de)

VERFAHREN ZUM MITEINANDER VERSIEGELN ODER VERSCHWEISSEN VON ZWEI ELEMENTEN

Title (fr)

PROCÈDE DE SCELLEMENT OU DE SOUDURE DE DEUX ÉLÉMENTS ENTRE EUX.

Publication

EP 1919822 A1 20080514 (FR)

Application

EP 06808248 A 20060821

Priority

- FR 2006050807 W 20060821
- FR 0552612 A 20050830

Abstract (en)

[origin: FR2890067A1] The method involves producing wettability areas (10, 11) on opposing faces of protective cover and electronic components, where one area has a layer of gold and a surface area (S2) greater than a surface area (S1) of the other area. A quantity of sealing material comprising indium is deposited on one of the areas by evaporation. The wettability area (11) is brought into contact with the deposited material. Temperature of a chamber containing the elements is raised to 250 degree Celsius in a non-oxidizing atmosphere, in order to seal the cover and the components to one another by remelting.

IPC 8 full level

B81C 99/00 (2010.01)

CPC (source: EP US)

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C-Set (source: EP US)

1. **H01L 2224/73103 + H01L 2924/00012**
2. **H01L 2924/1461 + H01L 2924/00**
3. **H01L 2224/13 + H01L 2924/00**
4. **H01L 2224/73203 + H01L 2924/00012**
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Citation (search report)

See references of WO 2007026093A1

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